



Material Content Data Sheet



Sales Product Name		SAF-C165-L25F HA		Issued		2. August 2018		
MA#		MA001182358						
Package		PG-TQFP-100-1		Weight*		701.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.727	1.96	1.96	19560	19560
leadframe	non noble metal	nickel	7440-02-0	77.443	11.03		110349	
	non noble metal	iron	7439-89-6	106.945	15.24	26.27	152387	262736
wire	noble metal	gold	7440-57-5	5.352	0.76	0.76	7626	7626
encapsulation	organic material	carbon black	1333-86-4	1.449	0.21		2065	
	plastics	epoxy resin	-	61.337	8.74		87401	
	inorganic material	silicondioxide	60676-86-0	420.184	59.87	68.82	598729	688195
leadfinish	non noble metal	tin	7440-31-5	6.211	0.89	0.89	8851	8851
plating	noble metal	silver	7440-22-4	6.180	0.88	0.88	8806	8806
glue	plastics	acrylic resin	-	0.593	0.08		845	
	noble metal	silver	7440-22-4	2.373	0.34	0.42	3381	4226
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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